

06-21-1999



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PATENT APPLICATION

Atty's Do. No.4591-78

Hana Ref. IE8081-US

WRD
6-9-99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of: **Gi-Won CHA**

Serial No. Filed herewith

Filed: June 9, 1999

For: **A POWER SUPPLY VOLTAGE BOOSTING CIRCUIT IN A SEMICONDUCTOR MEMORY DEVICE**

Box Assignment
Commissioner of Patents and Trademarks
Washington, D.C. 20231

09/328865



ASSIGNMENT TRANSMITTAL COVER SHEET

Please record the attached original document or copy thereof and return the recorded instrument to the undersigned.

1. Name of party conveying an interest: (1) **Gi-Won CHA**
2. Name and address of party(ies) receiving an interest: Samsung Electronics Co., Ltd.
416 Maetan-Dong, Palkal-Ku
Suwon-City, Kyungki-Do
Republic of Korea

3. Description of the interest conveyed:

Assignment Change of Name Security Agreement Merger Other:

Date of execution of attached document: (1) June 9, 1999

4. Application number(s) or patent number(s). Additional sheet attached? Yes No
If this document is being filed together with a new application, the execution date of the application is.

A. Patent Application No. Filed herewith B. Patent No.

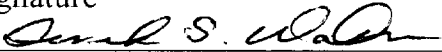
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5. Name and address of party to whom correspondence concerning document should be mailed:


Alan T. McCollom
MARGER, JOHNSON, & McCOLLOM, P.C.
1030 S.W. Morrison Street
Portland, Oregon 97205
Telephone: (503) 222-3613
6. Number of applications and patents involved: 1
7. Enclosed is our check for \$40.00 (check no. 02).
8. Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.
9. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

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Signature


Derek S. Watson

Respectfully submitted,


Alan T. McCollom
Reg. No. 28,881

Total number of pages comprising
cover sheet and attached assignment: 4

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PATENT APPLICATION
Atty's Do. No. 4591-78
Korean Priority Document No.: 98-21235
Hana Ref. No.: IE8081-US

ASSIGNMENT

U.S.A. Patent Application
Sole or Joint
For Inventions Made Outside U.S.A.
Executed With Application

In consideration of the sum of Ten Dollars (10.00) and other good and valuable considerations paid to each of the undersigned, to wit:

(1) **Gi-Won CHA**

X if continued on separate page

the receipt and sufficiency of which are hereby acknowledged by the undersigned who hereby sell(s), assign(s) and transfer(s) unto:

**SAMSUNG ELECTRONICS CO., LTD.
416 MAETAN-DONG, PALDAL-KU
SUWON-CITY, KYUNGKI-DO
REPUBLIC OF KOREA**

(hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States Of America as defined in 35 U.S.C. §1.00, in and to the invention known as:

**A POWER SUPPLY VOLTAGE BOOSTING CIRCUIT IN A SEMICONDUCTOR
MEMORY DEVICE**

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisionals, continuations, substitutes, and reissues thereof; and all resulting patents and the undersigned hereby authorizes and requests the United States Assistant Commissioner of Patents to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

And the undersigned hereby agrees to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

Full name of sole or first inventor: **GI-won CHA**

Inventor's signature: **GIWON CHA**

June 9, 1999
(Date)

Residence: **Korea**

Citizenship: **Korea**

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